

Di Wu

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EDUCATION

- **University of Science and Technology of China** [🌐] Hefei, China
Bachelor of Science in Applied Physics Sep. 2021 - July 2025 (expected)
 - **GPA (overall):** 3.95/4.30; **GPA (major):** 4.00/4.30; **Ranking:** 2/50
 - **Relevant Coursework :**

Computer Architecture H	93/100	Computer Organization	96/100
Computer Programming A	95/100	Computational Method	95/100
Computer Network	87/100	Operation System	85/100
Linear Algebra B1	100/100	Digital Circuits Experiment H	93/100
Probability Theory & Math. Statistics	96/100	Digital Circuits	92/100
Mathematical Analysis B	93/100	Fast Electronics	93/100
 - **Honors & Rewards**

Outstanding Student Scholarship (First Prize) (1/38)	Nov. 2022
National Encouragement Scholarship	Oct. 2023
Third Prize in "Challenge Cup" National Extracurricular Acad. & Tech. Works Competition	Aug. 2024
Outstanding Student Scholarship	Sep. 2024
Talented Class Scholarship	Oct. 2024
National Encouragement Scholarship	Oct. 2024
Outstanding Student Scholarship (First Prize) (1/48)	Oct. 2024

RESEARCH EXPERIENCE

- **Chair, the System and Networking Group, NUS** July 2024 - Present
Supervisor: Prof. **Bingsheng He** and Prof. **Yao Chen**
Project I: *Content Addressable Memory on FPGA*
 - Conducted analysis of FPGA-based CAM, enhancing the theoretical foundation for this DSA design.
 - Proposed a configurable DSP-based CAM architecture with high-performance and multi-query support.
 - Implemented an extensible CAM kernel with a hybrid HLS and RTL architecture on FPGA, now publicly available on GitHub.
 - Submitted a research paper detailing the design to DAC'25.
- **Research Assistant, Institute of ASIC, USTC** June 2023 - June 2024
Supervisor: Prof. **Lei Zhao**
Project I: *Test and analysis of a SerDes prototype chip based on 180 nm CMOS process*
 - Designed an efficient testing scheme tailored to the chip's specific structure and key testing metrics.
 - Investigated chip configurations and built test code using Verilog HDL.
 - Utilized FPGA to test the relevant index shortness, providing data to enhance the feed-through design.Project II: *Simulation of the chip wiring S parameters*
 - Built the simulation models for chip wiring based on the encapsulated drawings.
 - Determined the S parameters to accommodate the shape material wiring, providing important information for the post-simulation circuit analysis.
- **Research Assistant, Institute of "Subtle Discernment", USTC** Jan. 2023 - May 2023
Supervisor: Prof. **Jie Zeng**
Project I: *The effect of surface modification on electrocatalytic ammonia synthesis*
 - Analyzed catalyst surface modifications and their effects on ammonia synthesis performance.
 - Examined the impact and mechanisms of surface modification, completing key technical metrics for publication.

PUBLICATIONS

C=CONFERENCE, J=JOURNAL, O=ORAL PRESENTATION, S=IN SUBMISSION, T=THESIS

- [S.1] Yao Chen, Feng Yu, **Di Wu**, Weng-Fai Wong and Bingsheng He. "**Configurable DSP-Based CAM Architecture for Data-Intensive Applications on FPGAs**," in *2025 62th Design Automation Conference (DAC)*. 
- [O.1] Jiacheng Guo, Jiajun Qin, Lei Zhao, **Wu Di**, Xinyu Bin, "**A 4×6.25-Gbs Serial Link Transmitter Core in 0.18- μ m CMOS for high-speed front-end ASICs**," in *2024 24th IEEE Real Time Conference*.
- [J.1] Yuheng Wu, Xiangdong Kong, Yechao Su, Jiankang Zhao, Yiling Ma, Tongzheng Ji, **Di Wu**, Junyang Meng, Yan Liu, Zhigang Geng, Jie Zeng, "**Thiol Ligand-Modified Au for Highly Efficient Electroreduction of Nitrate to Ammonia**," in *Precis. Chem.* 2024, 2, 3, 112–119.

SKILLS & INTERESTS

- **Programming Languages:** Verilog/System Verilog, C/C++, Python, L^AT_EX
- **Developer Tools:** Vivado, Vitis
- **Technologies/Frameworks:** Linux, Git, HLS, CUDA, Pytorch
- **Interests:** USTC Students Chorus Member, USTC Badminton Club Deputy Minister